Vincotech

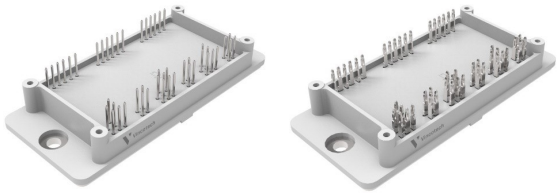
30-P2126PA100M701-L289F719Y
30-F2126PA100M701-L289F719
datasheet

flow PACK 2 **1200 V / 100 A**

Features

- IGBT Mitsubishi gen 7 technology with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Built-in NTC

flow 2 17mm housing



Solder pin Press-fit pin

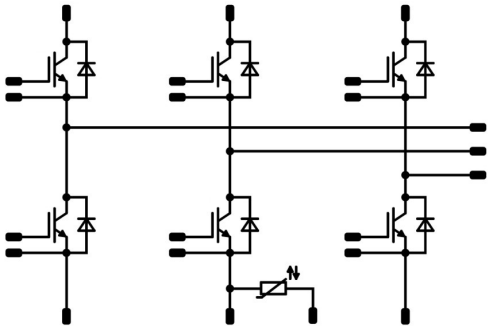
Target applications

- Industrial Drives
- Power Supply
- UPS

Types

- 30-P2126PA100M701-L289F719Y
- 30-F2126PA100M701-L289F719

Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Half-Bridge Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	109	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	232	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Half-Bridge Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	89	A
Repetitive peak forward current	I_{FRM}		200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	165	W
Maximum junction temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage t_p = 2 s	4000	V
Creepage distance			min. 12,7	mm
Clearance			min. 12,7	mm
Comparative Tracking Index	CTI		> 200	

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Half-Bridge Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,01	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		100	25 125 150		1,61 1,82 1,91	2,05	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			110	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		21000		pF
Output capacitance	C_{oes}							700		
Reverse transfer capacitance	C_{res}							280		
Gate charge	Q_g		15	600	100	25		650		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material λ = 3,4 W/mK						0,41		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 2 Ω R_{gon} = 2 Ω	±15	600	100	25 125 150		118 118 118		ns
Rise time	t_r					25 125 150		10 12 13		
Turn-off delay time	$t_{d(off)}$					25 125 150		174 200 206		
Fall time	t_f					25 125 150		83 96 107		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 11,6 µC Q_{rFWD} = 17,3 µC Q_{rFWD} = 19,2 µC				25 125 150		3,255 4,868 5,368		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		6,605 8,774 9,490		

Characteristic Values

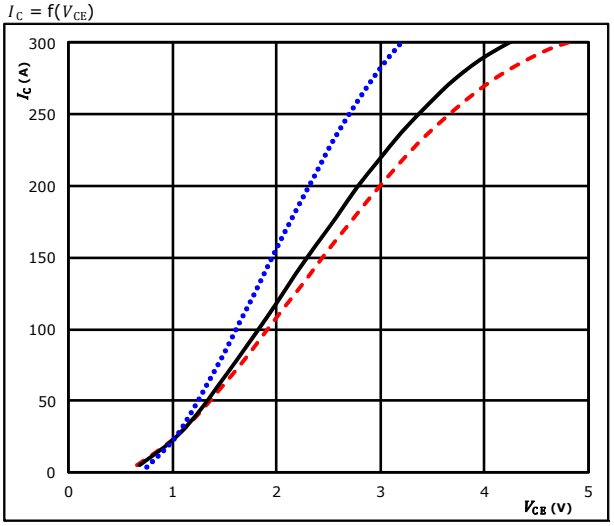
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Half-Bridge Diode										
Static										
Forward voltage	V_F				100	25 125 150		1,82 1,96 1,97	2,1	V
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material λ = 3,4 W/mK						0,58		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 9387 A/µs di/dt = 7872 A/µs di/dt = 8350 A/µs	±15	600	100	25 125 150		178 166 165		A
Reverse recovery time	t_{rr}					25 125 150		149 312 339		ns
Recovered charge	Q_r					25 125 150		11,601 17,270 19,181		µC
Reverse recovered energy	E_{rec}					25 125 150		5,138 7,753 8,588		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		4044 2649 2147		A/µs
Thermistor										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1486 Ω				100	-5		+5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1%				25		3962		K
B-value	$B_{(25/100)}$	Tol. ±1%				25		4000		K
Vincotech NTC Reference									I	

Half-Bridge Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

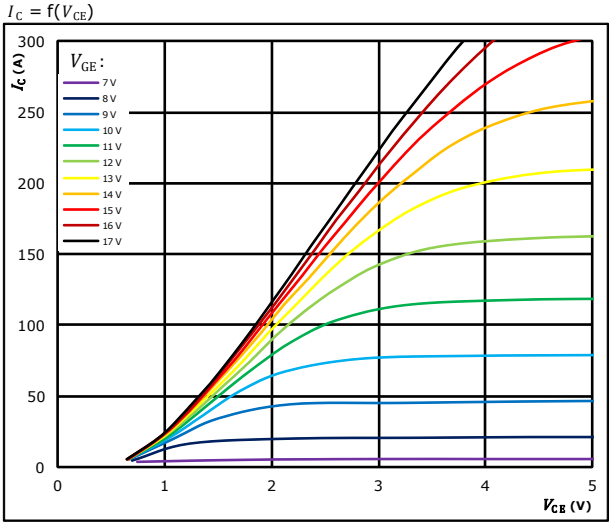


t_p =	250	µs		25 °C
V_{GE} =	15	V	T_j:	125 °C
				150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

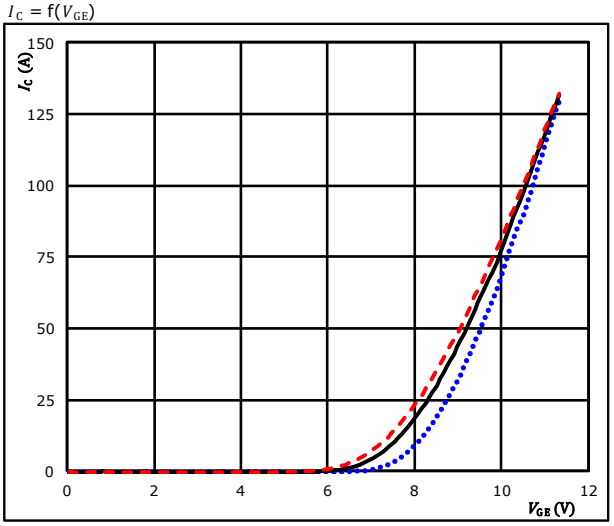


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

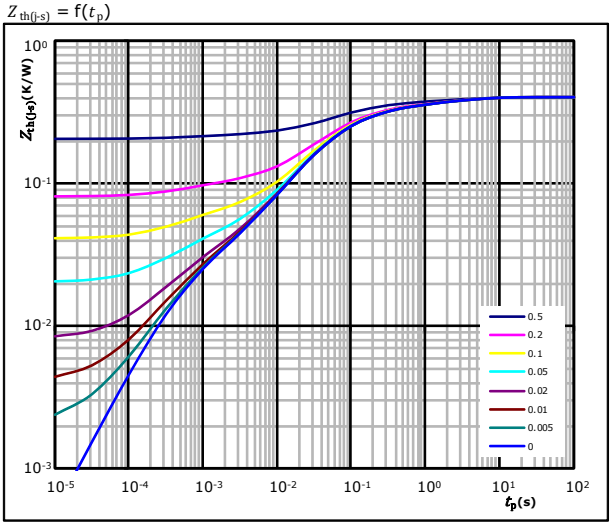


t_p =	100	µs		25 °C
V_{CE} =	10	V	T_j:	125 °C
				150 °C

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,41	K/W

IGBT thermal model values

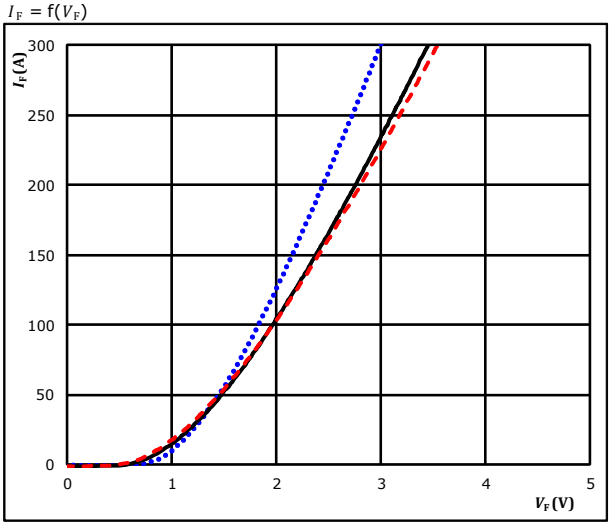
R (K/W)	τ (s)
4,27E-02	4,21E+00
6,06E-02	6,46E-01
1,38E-01	1,09E-01
1,39E-01	2,79E-02
1,46E-02	2,35E-03
1,57E-02	4,10E-04

Half-Bridge Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



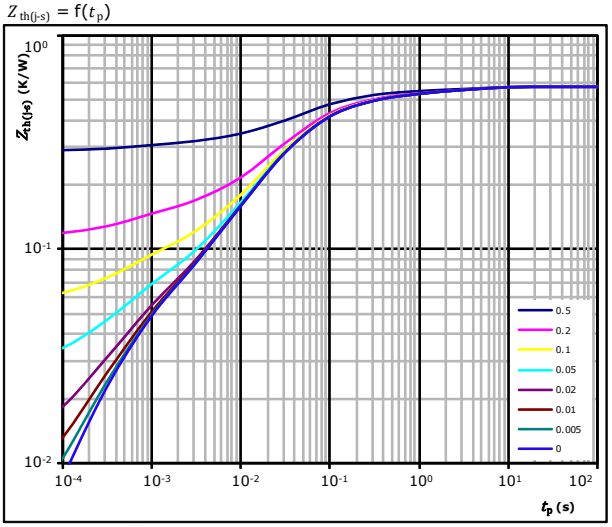
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,58 K/W

FWD thermal model values

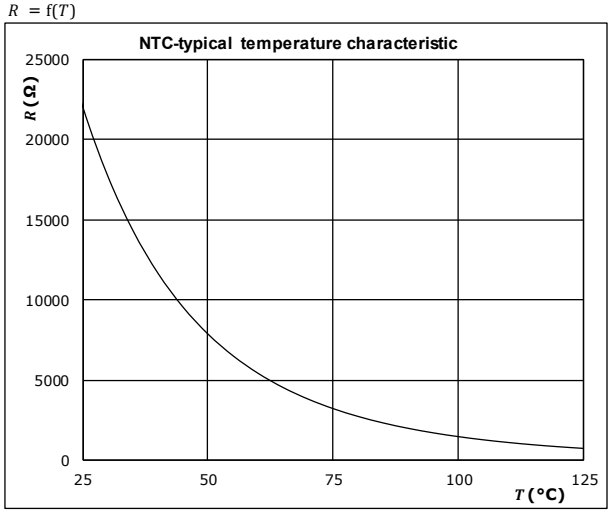
R (K/W)	τ (s)
4,89E-02	3,41E+00
7,07E-02	4,06E-01
2,02E-01	7,46E-02
1,90E-01	2,27E-02
3,24E-02	3,47E-03
3,35E-02	4,78E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

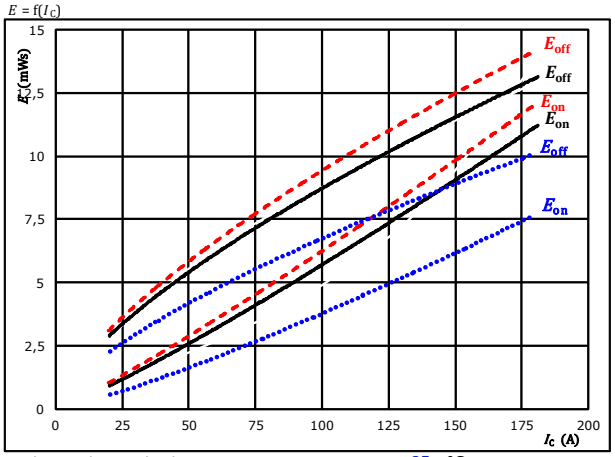


Halfbridge Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



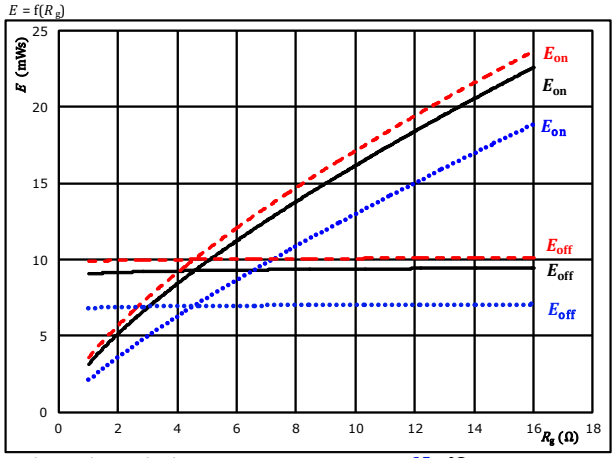
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	2	Ω		150 °C	
R_{goff} =	2	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



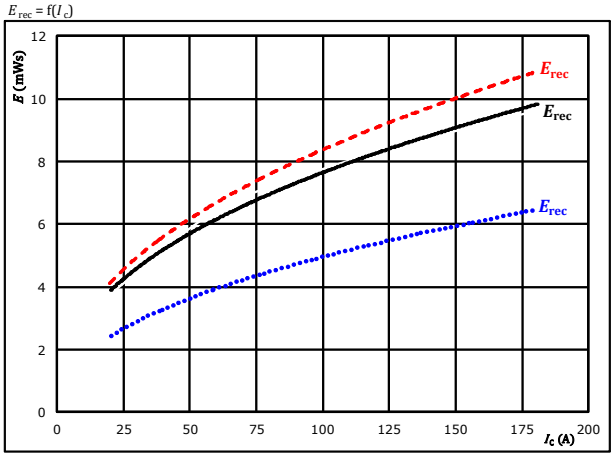
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	100	A		150 °C	

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



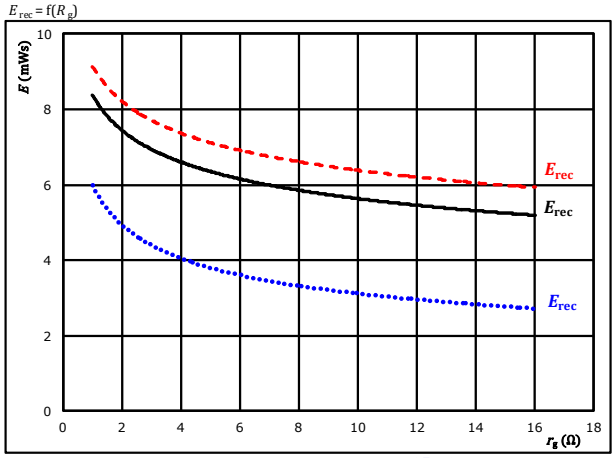
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
R_{gon} =	2	Ω		150 °C	

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

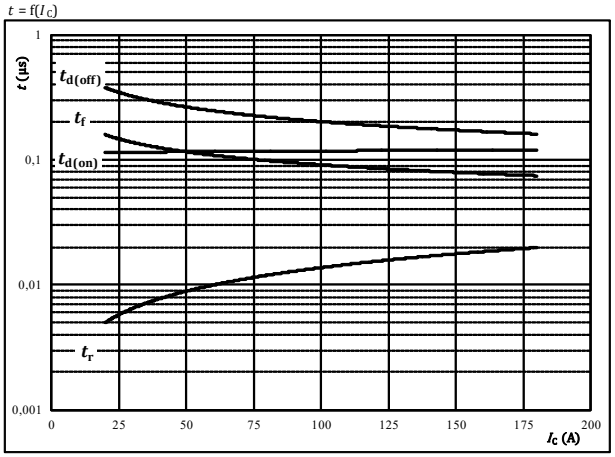
V_{CE} =	600	V	T_j:	25 °C	
V_{GE} =	±15	V		125 °C	
I_C =	100	A		150 °C	

Halfbridge Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



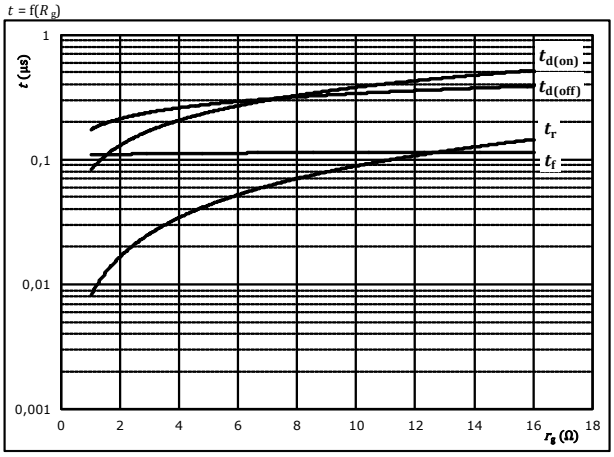
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	2	Ω
R_{goff} =	2	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



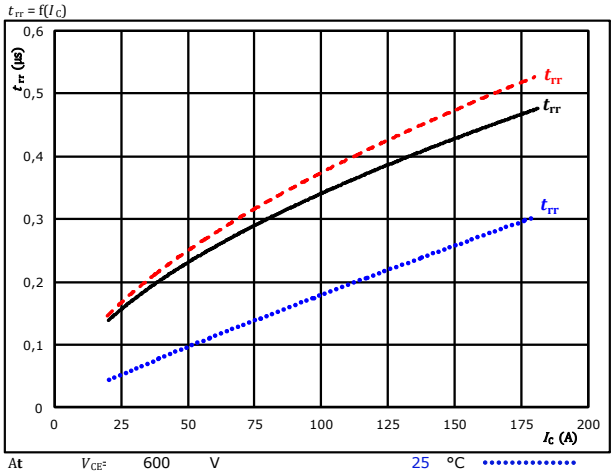
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	100	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

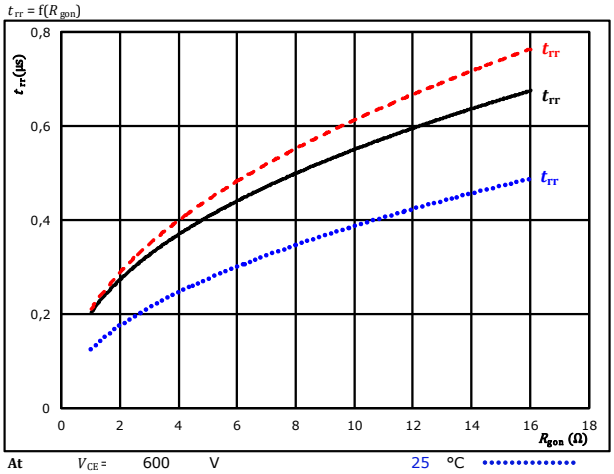


At	V_{CE} =	600	V		25 °C
	V_{GE} =	±15	V	T_j:	125 °C
	R_{gon} =	2	Ω		150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



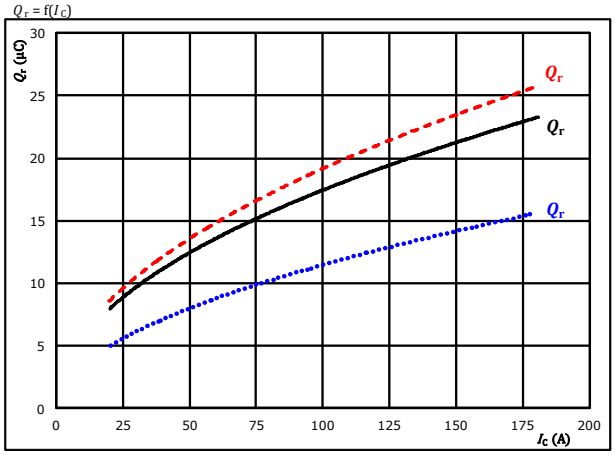
At	V_{CE} =	600	V		25 °C
	V_{GE} =	±15	V	T_j:	125 °C
	I_C =	100	A		150 °C

Halfbridge Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

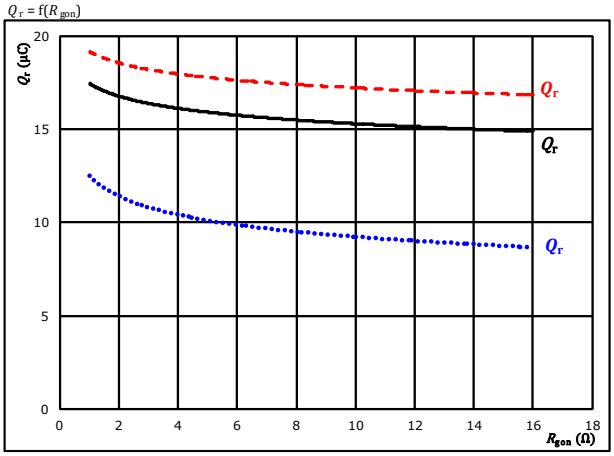


At						
	V_{CE} =	600	V		25 °C	·····
	V_{GE} =	±15	V	T_j:	125 °C	———
	R_{gon} =	2	Ω		150 °C	– – –

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

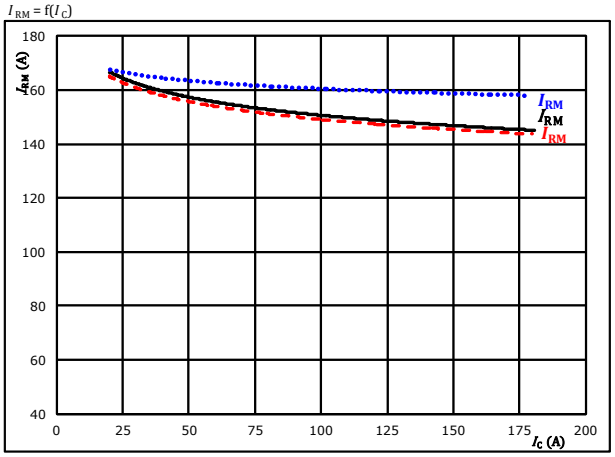


At						
	V_{CE}=	600	V		25 °C	·····
	V_{GE} =	±15	V	T_j:	125 °C	———
	I_C=	100	A		150 °C	– – –

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

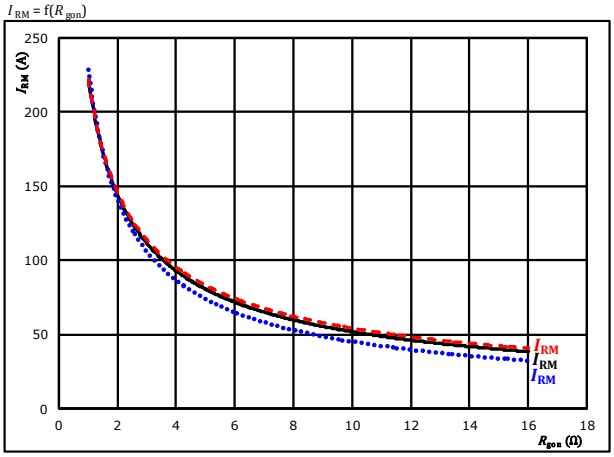


At						
	V_{CE}:	600	V		25 °C	·····
	V_{GE} =	±15	V	T_j:	125 °C	———
	R_{gon} =	2	Ω		150 °C	– – –

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



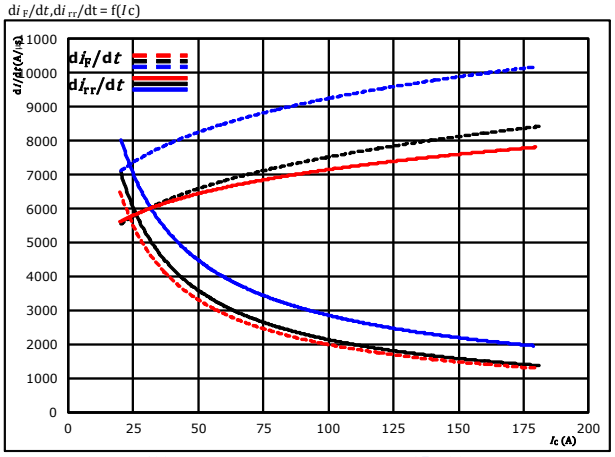
At						
	V_{CE} =	600	V		25 °C	·····
	V_{GE} =	±15	V	T_j:	125 °C	———
	I_C =	100	A		150 °C	– – –

Halfbridge Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

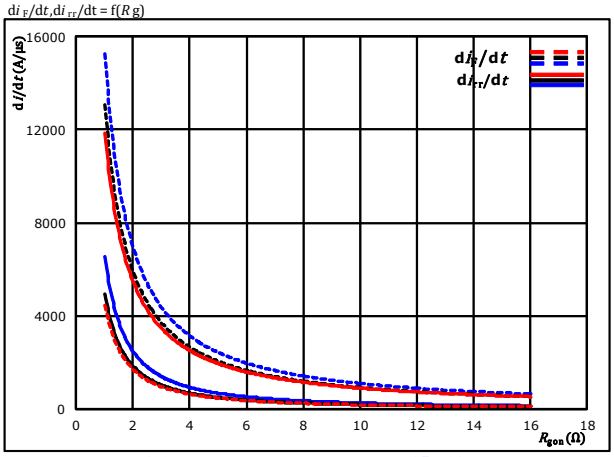


At	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	R_{gon} =	2	Ω		150 °C	

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_g)$

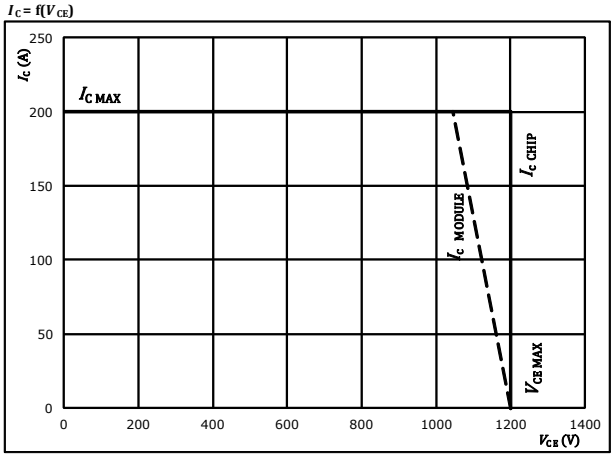


At	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	I_C =	100	A		150 °C	

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

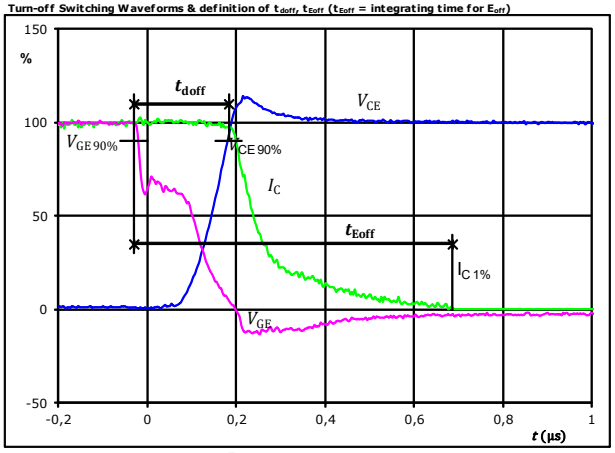
T_j =	175	°C
R_{gon} =	2	Ω
R_{goff} =	2	Ω

Halfbridge Switching Definitions

General conditions		
T_j	=	125 °C
R_{gon}	=	2 Ω
R_{goff}	=	2 Ω

figure 1. IGBT

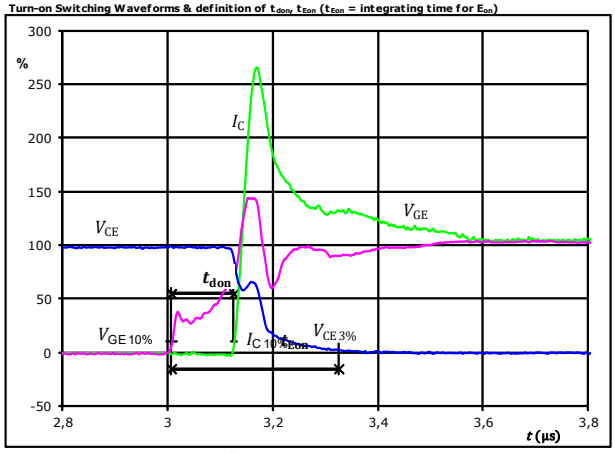
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	100	A
t_{doff} =	0,200	µs
t_{Eoff} =	0,717	µs

figure 2. IGBT

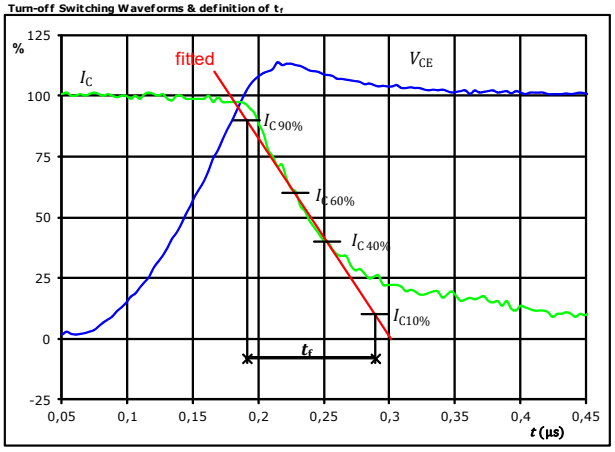
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	100	A
t_{don} =	0,118	µs
t_{Eon} =	0,318	µs

figure 3. IGBT

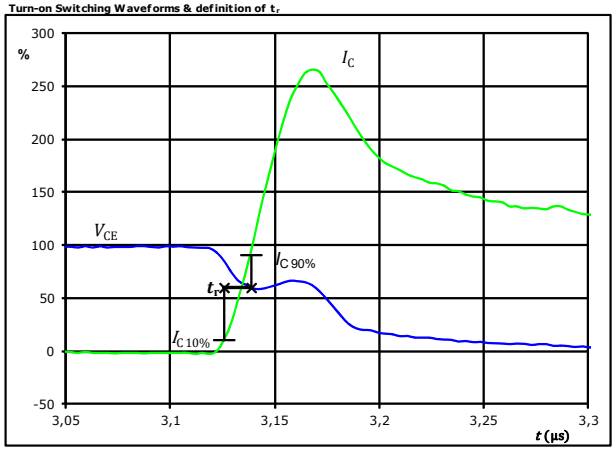
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	100	A
t_f =	0,096	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

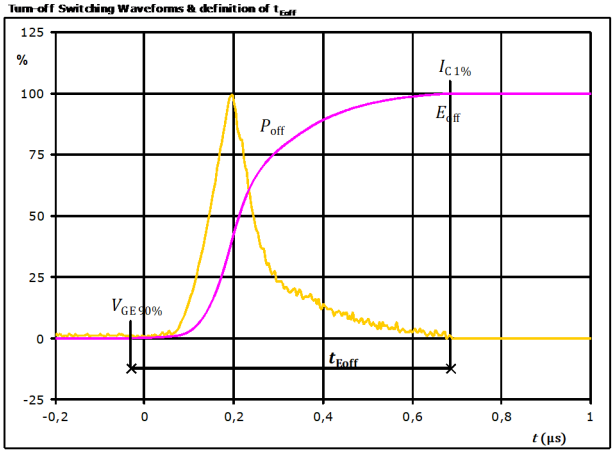


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	100	A
t_r =	0,012	µs

Halfbridge Switching Characteristics

figure 5. **IGBT**

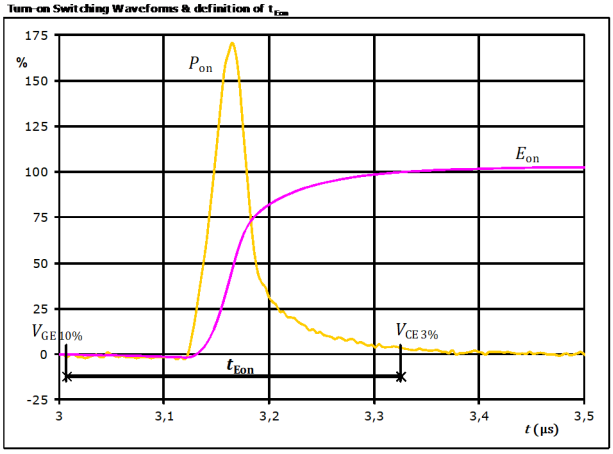
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	59,87	kW
$E_{off}(100\%)$ =	8,77	mJ
t_{Eoff} =	0,72	µs

figure 6. **IGBT**

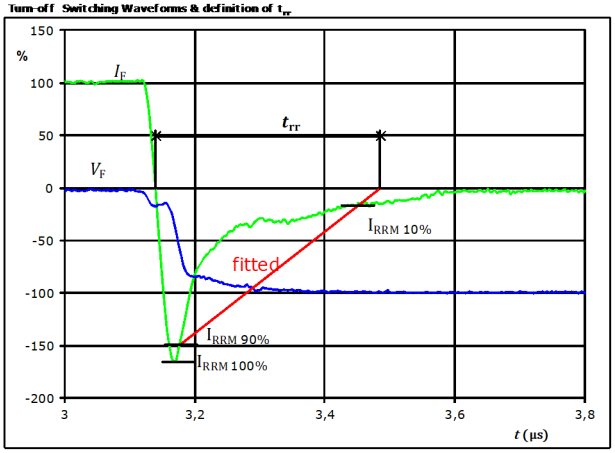
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	59,87	kW
$E_{on}(100\%)$ =	4,87	mJ
t_{Eon} =	0,32	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

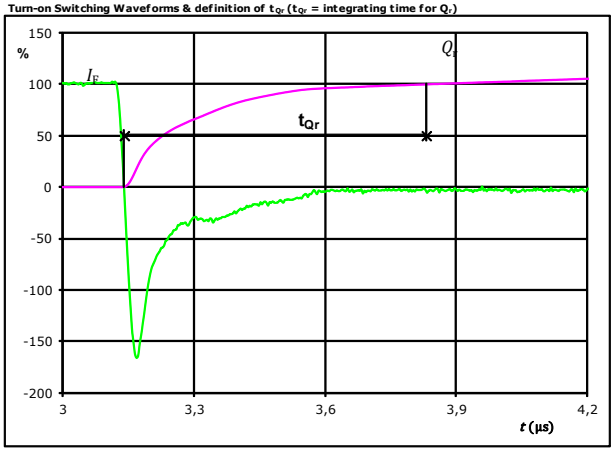


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	100	A
$I_{RRM}(100\%)$ =	-166	A
t_{rr} =	0,312	µs

Halfbridge Switching Characteristics

figure 8. **FWD**

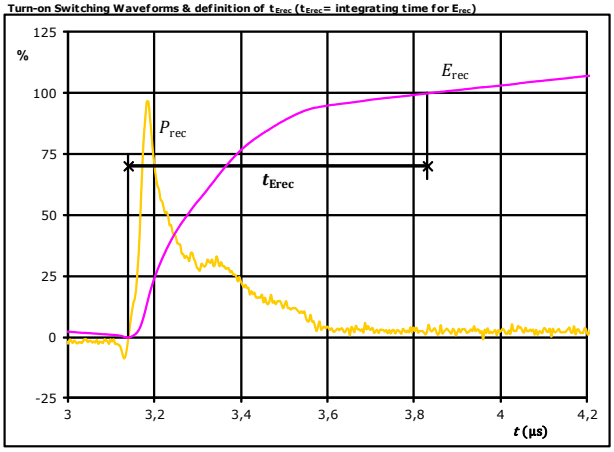
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



$I_F(100\%)$ =	100	A
$Q_r(100\%)$ =	17,27	µC
t_{Qr} =	0,69	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec}= integrating time for E_{rec})



$P_{rec}(100\%)$ =	59,87	kW
$E_{rec}(100\%)$ =	7,75	mJ
t_{Erec} =	0,69	µs

Vincotech

30-P2126PA100M701-L289F719Y
30-F2126PA100M701-L289F719
datasheet

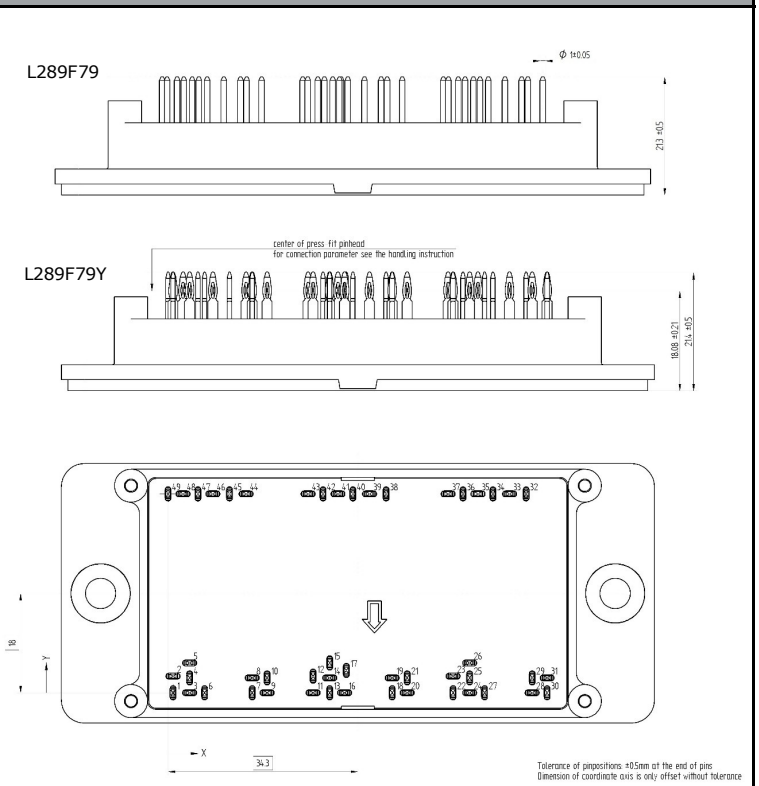
Ordering Code & Marking

Version	Ordering Code
with thermal paste 17mm housing with Press-fit pins	30-P2126PA100M701-L289F719Y-/3/
with thermal paste 17mm housing with solder pins	30-F2126PA100M701-L289F719-/3/
without thermal paste 17mm housing with Press-fit pins	30-P2126PA100M701-L289F719Y
without thermal paste 17mm housing with solder pins	30-F2126PA100M701-L289F719

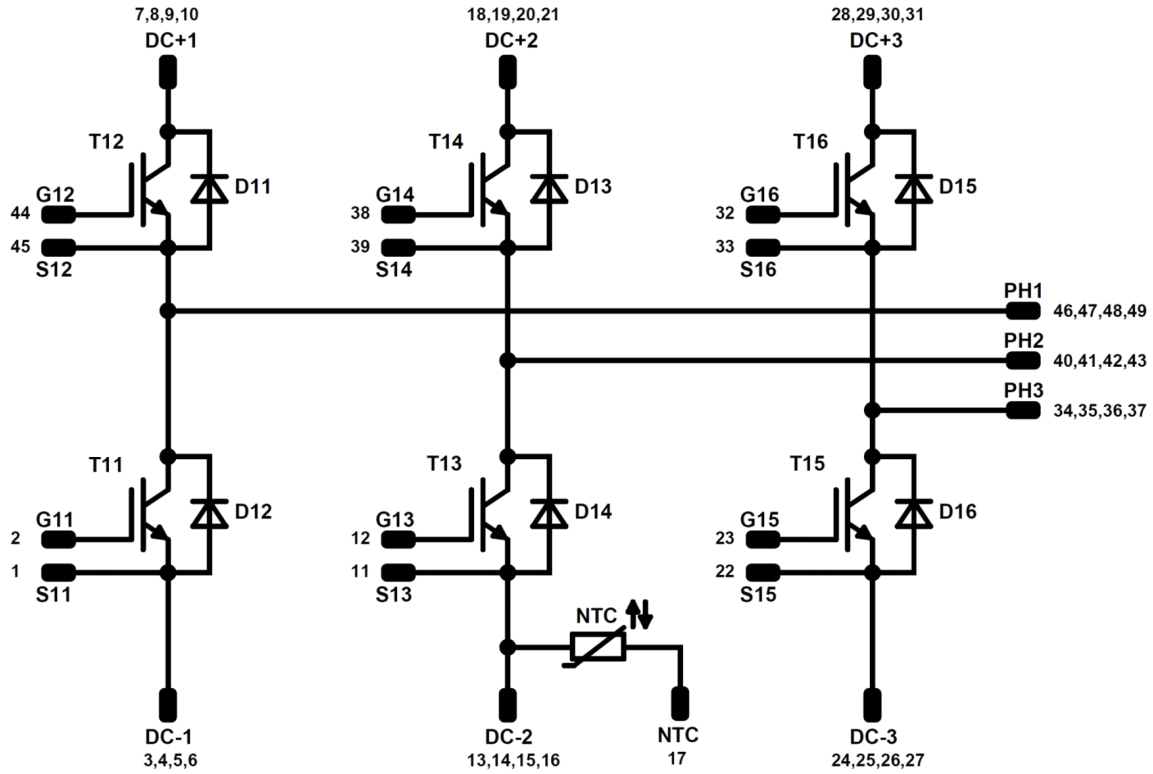
Text	**Name**		**Date code**	**UL & VIN**	**Lot**	**Serial**
	NN-NNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

Pin table [mm]				Pin table [mm]			
Pin	X	Y	Function	Pin	X	Y	Function
1	0,9	0	S11	30	68,5	0	DC+3
2	0,9	3	G11	31	68,5	2,7	DC+3
3	3,9	0	DC-1	32	64,7	36	G16
4	3,9	2,7	DC-1	33	61,7	36	S16
5	3,9	5,4	DC-1	34	58,7	36	PH3
6	6,6	0	DC-1	35	56	36	PH3
7	15,2	0	DC+1	36	53,3	36	PH3
8	15,2	2,7	DC+1	37	50,6	36	PH3
9	17,9	0	DC+1	38	39,4	36	G14
10	17,9	2,7	DC+1	39	36,4	36	S14
11	26,2	0	S13	40	33,4	36	PH2
12	26,2	3	G13	41	30,7	36	PH2
13	29,2	0	DC-2	42	28	36	PH2
14	29,2	2,7	DC-2	43	25,3	36	PH2
15	29,2	5,4	DC-2	44	14,1	36	G12
16	31,9	0	DC-2	45	11,1	36	S12
17	32,2	4,05	NTC	46	8,1	36	PH1
18	40,5	0	DC+2	47	5,4	36	PH1
19	40,5	2,7	DC+2	48	2,7	36	PH1
20	43,2	0	DC+2	49	0	36	PH1
21	43,2	2,7	DC+2				
22	51,5	0	S15				
23	51,5	3	G15				
24	54,5	0	DC-3				
25	54,5	2,7	DC-3				
26	54,5	5,4	DC-3				
27	57,2	0	DC-3				
28	65,8	0	DC+3				
29	65,8	2,7	DC+3				



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11,T12,T13 T14,T15,T16	IGBT	1200 V	100 A	Half-Bridge Switch	
D11,D12,D13 D14,D15,D16	FWD	1200 V	100 A	Half-Bridge Diode	
NTC	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 36	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 2 packages see vincotech.com website.

Package data
Package data for *flow* 2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
30-x2126PA100M7-L289F79x-D1-14	26 Aug. 2019		